EXHIBIT A



Disclosure FIS8-2002-0306

Prepared for and/or by an IBM Attorney - IBM Confidential

Created By Sadanand V Deshpande Last Modified By Judy Paolillo

Required fields are marked with the asterisk $(\begin{subarray}{c}^\star\end{subarray})$ and must be filled in to complete the form .

*Title of disclosure (in English)

STI stress modification by Nitrogen plasma treatment for improving performance in small (RX) width devices.

Summary

Status		Final Decision (File)						
Final Deadline								
Final Deadline								
Reason								
Docket Family		FIS9-2003-0078						
*Processing Location		Fishkill						
*Functional Area	select	(KBG) KBG CHEN; CMOS-6X/HPLS						
Attorney/Patent Professional Joseph P Abate/Fishkill/IBM								
IDT Team	select	Oleg Gluschenkov/Fishkill/IBM William Devine/Fishkill/IBM DOMINIC SCHEPIS/Fishkill/IBM David Hanson/Fishkill/IBM Thomas Dyer/Fishkill/IBM Noah Zamdmer/Fishkill/IBM DURESETI CHIDAMBARRAO/Fishkill/IBM Werner Rausch/Fishkill/IBM Samuel Fung/Fishkill/IBM						
Submitted Date								
*Owning Division	select	MD						
Incentive								
Program								
Lab								
*Technology		101N2						
Code								
PVT Score								

Inventors with a Blue Pages entry

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Main Idea for Disclosure FIS8-2002-0306

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Archived On

Title of disclosure (in English)

STI stress modification by Nitrogen plasma treatment for improving performance in small (RX) width devices.

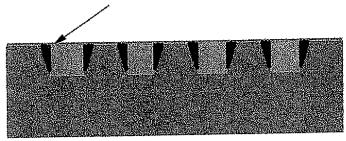
Main Idea of disclosure

1. Describe your invention, stating the problem solved (if appropriate), and indicating the advantages of using the invention.

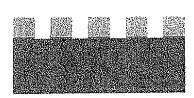
Use of DPN (nitrogen plasma treatment) or RPN (remote plasma nitridation) to treat the shallow trench region to modulate stress in small Rx devices.

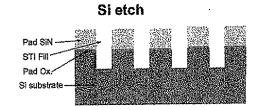
In a standard process flow, oxidation from gate oxides and gate reoxidation can create compression in the active areas leading to degradation for NFETs and improvement for PFETS. Recently we have observed up to 17% Ion degradation at a fixed loff for NFET and up to 17 % improvement in PFET in small Rx devices. This invention overcomes the degradation and also provides a method to retain the enhancement for the PFET. The birds beaking is shown below:

Birds' beak caused by oxidation

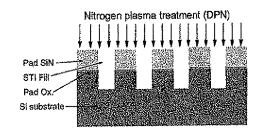


Standard shallow trench isolation formation (hard-mask process).

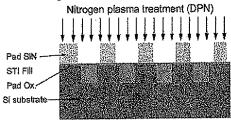




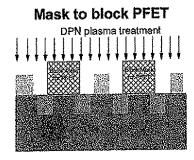
The STI corners can be treated with Plasma nitridation using a source such as a DPN tool at various steps in the process to reduce the bird's beak formation.



SiO2 deglaze with optional SIN pull-back



In a preferred embodiment, a mask may be used to block the PFET while allowing the NFET active atea, STI corners to receive the plasma treatment. Blocking the PFET during the nitridation process enables the longitudinal direction to be under compressive strain thereby enhancing the PFET mobility. The fact that this invention reduces the bird'sbeak effect reduces the compression which can degrade NFET mobility by a significant amount.



2. How does the invention solve the problem or achieve an advantage, (a description of "the invention", including figures inline as appropriate)?

- 3. If the same advantage or problem has been identified by others (inside/outside IBM), how have those others solved it and does your solution differ and why is it better?
- 4. If the invention is implemented in a product or prototype, include technical details, purpose, disclosure details to others and the date of that implementation.